

Elektrische Eigenschaften / Electrical properties

Zieldaten Target data

Höchstzulässige Werte / Maximum rated values

| Netzdiode, -thyristor / Rectifierdiode, -thyristor | | | | | |
|--|--|----------------|----------|------------------------|--|
| Periodische Spitzensperrspannung repetitive peak reverse voltage | $T_{vj} = -40^{\circ}\text{C} \dots T_{vj\text{max}}$ | V_{RRM} | 1600 | V | |
| Durchlaßstrom-Grenzeffektivwert (pro Element) RMS on-state current (per chip) | | I_{TRMSM} | 60 | A | |
| Ausgangsstrom output current | $T_C = 85^{\circ}\text{C}$ | I_d | 125 | A | |
| Stoßstrom-Grenzwert surge current | $T_{vj} = 25^{\circ}\text{C}, t_p = 10\text{ms}$ $T_{vj} = T_{vj\text{max}}, t_p = 10\text{ms}$ | I_{TSM} | 650 | A | |
| | | | 550 | A | |
| Grenzlastintegral I^2t -value | $T_{vj} = 25^{\circ}\text{C}, t_p = 10\text{ms}$ $T_{vj} = T_{vj\text{max}}, t_p = 10\text{ms}$ | I^2t | 2100 | A^2s | |
| | | | 1500 | A^2s | |
| Kritische Stromsteilheit critical rate of rise of on-state current | DIN IEC 747-6 $f = 50\text{Hz}, i_{GM} = 0,6\text{A}, di/dt = 0,6\text{A}/\mu\text{s}$ | $(di/dt)_{cr}$ | 120 | $\text{A}/\mu\text{s}$ | |
| Kritische Spannungssteilheit critical rate of rise of off-state voltage | $T_{vj} = T_{vj\text{max}}, V_D = 0,67 V_{DRM}$ 8. Kennbuchstabe / 8th letter F | $(dv/dt)_{cr}$ | 1000 | $\text{V}/\mu\text{s}$ | |
| IGBT | | | | | |
| Kollektor-Emitter-Sperrspannung collector-emitter voltage | | V_{CES} | 1200 | V | |
| Kollektor-Dauergleichstrom DC-collector current | | I_C | 75 | A | |
| Periodischer Kollektor-Spitzenstrom repetitive peak collector current | $t_p = 1\text{ms}$ | I_{CRM} | 150 | A | |
| Gesamt-Verlustleistung total power dissipation | $T_C = 25^{\circ}\text{C}$ | P_{tot} | 400 | W | |
| Gate-Emitter Spitzenspannung gate-emitter peak voltage | | V_{GE} | ± 20 | V | |
| Schnelle Diode / Fast diode | | | | | |
| Periodische Spitzensperrspannung repetitive peak reverse voltage | | V_{RRM} | 1200 | V | |
| Dauergleichstrom DC forward current | | I_F | 35 | A | |
| Periodischer Spitzenstrom repetitive peak forward current | $t_p = 1\text{ms}$ | I_{FRM} | 70 | A | |
| Modul | | | | | |
| Isolations-Prüfspannung insulation test voltage | RMS, $f = 50\text{Hz}, t = 1\text{min}$ | V_{ISOL} | 2,5 | kV | |

Charakteristische Werte / Characteristic values

| Netzdiode, -thyristor / Rectifierdiode, -thyristor | | | min. | typ. | max. | |
|--|--|------------|------|------|------|------------------|
| Durchlaßspannung forward voltage | $T_{vj} = T_{vj\text{max}}, I_F = 100\text{A}$ | V_F | | 1,55 | | V |
| Schleusenspannung threshold voltage | $T_{vj} = T_{vj\text{max}}$ | $V_{(TO)}$ | | | 0,75 | V |
| Ersatzwiderstand forward slope resistance | $T_{vj} = T_{vj\text{max}}$ | r_T | | | 6,3 | $\text{m}\Omega$ |

Elektrische Eigenschaften / Electrical properties

Zieldaten Target data

Charakteristische Werte / Characteristic values

| | | | min. | typ. | max. | |
|--|--|---------------------|------|------|------|----------------|
| Netzdiode, -thyristor / Rectifierdiode, -thyristor | | | | | | |
| Zündstrom gate trigger current | $T_{vj} = 25^{\circ}\text{C}, v_D = 6\text{V}$ | I_{GT} | | | 150 | mA |
| Zündspannung gate trigger voltage | $T_{vj} = 25^{\circ}\text{C}, v_D = 6\text{V}$ | V_{GT} | | | 2,5 | V |
| Nicht zündender Steuerstrom gate non-trigger current | $T_{vj} = T_{vj\text{ max}}, v_D = 6\text{V}$ | I_{GD} | | | 5,0 | mA |
| | $T_{vj} = T_{vj\text{ max}}, v_D = 0,5 V_{DRM}$ | | | | 2,5 | mA |
| Nicht zündende Steuerspannung gate non-trigger voltage | $T_{vj} = T_{vj\text{ max}}, v_D = 0,5 V_{DRM}$ | V_{GD} | | | 0,2 | V |
| Haltestrom holding current | $T_{vj} = 25^{\circ}\text{C}, v_D = 6\text{V}, R_A = 5\Omega$ | I_H | | | 200 | mA |
| Einraststrom latching current | $T_{vj} = 25^{\circ}\text{C}, v_D = 6\text{V}, R_{GK} \geq 20\Omega$ $i_{GM} = 0,6\text{A}, di/dt = 0,6\text{A}/\mu\text{s}, t_j = 10\mu\text{s}$ | I_L | | | 600 | mA |
| Vorwärts- und Rückwärts-Sperrstrom forward off-state and reverse currents | $T_{vj} = T_{vj\text{ max}}$ $v_D = V_{DRM}, v_R = V_{RRM}$ | i_D, i_R | | | 10 | mA |
| Zündverzögerung gate controlled delay time | DIN IEC 747-6 $T_{vj} = 25^{\circ}\text{C}, i_{GM} = 0,6\text{A}, di/dt = 0,6\text{A}/\mu\text{s}$ | t_{gd} | | | 1,2 | μs |
| Freiwerdezeit circuit commutated turn-off time | $T_{vj} = T_{vj\text{ max}}, i_{TM} = 50\text{A}$ $v_{RM} = 100\text{V}, v_{DM} = 0,67 V_{DRM}$ $d_{vD}/dt = 20\text{V}/\mu\text{s}, -di/dt = 10\text{A}/\mu\text{s}$ 7. Kennbuchstabe / 7th letter O | t_q | | | 190 | μs |
| IGBT | | | | | | |
| Kollektor-Emitter Sättigungsspannung collector-emitter saturation voltage | $T_{vj} = 25^{\circ}\text{C}, i_C = 75\text{A}, v_{GE} = 20\text{V}$ | $V_{CE\text{ sat}}$ | | | 2,1 | V |
| | $T_{vj} = 125^{\circ}\text{C}, i_C = 75\text{A}, v_{GE} = 20\text{V}$ | | | | 2,4 | |
| Gate-Emitter-Schwellspannung gate-emitter threshold voltage | $T_{vj} = 25^{\circ}\text{C}, i_C = 3\text{mA}, v_{GE} = v_{CE}$ | $V_{GE(TO)}$ | 4,5 | 5,5 | 6,5 | V |
| Eingangskapazität input capacitance | $T_{vj} = 25^{\circ}\text{C}, f_0 = 1\text{MHz},$ $v_{CE} = 25\text{V}, v_{GE} = 0\text{V}$ | C_{ies} | | | 5,1 | nF |
| Kollektor-Emitter Reststrom collector-emitter cut-off current | $T_{vj} = 25^{\circ}\text{C}, v_{CE} = 1200\text{V}, v_{GE} = 0\text{V}$ | i_{CES} | | | 10 | μA |
| | $T_{vj} = 125^{\circ}\text{C}, v_{CE} = 1200\text{V}, v_{GE} = 0\text{V}$ | | | | 500 | |
| Gate-Emitter Reststrom gate leakage current | $T_{vj} = 25^{\circ}\text{C}, v_{CE} = 0\text{V}, v_{GE} = 20\text{V}$ | i_{GES} | | | 400 | nA |
| Emitter-Gate Reststrom gate-leakage current | $T_{vj} = 25^{\circ}\text{C}, v_{CE} = 0\text{V}, v_{EG} = 20\text{V}$ | i_{EGS} | | | 400 | nA |
| Schnelle Diode / Fast diode | | | | | | |
| Durchlaßspannung forward voltage | $T_{vj} = 25^{\circ}\text{C}, i_F = 35\text{A}$ | V_F | | | 1,8 | V |
| | $T_{vj} = 125^{\circ}\text{C}, i_F = 35\text{A}$ | | | | 1,7 | |
| Sperrverzögerungsladung recovered charge | $i_{FM} = 35\text{A}, -di/dt = 900\text{A}/\mu\text{s}, v_R = 600\text{V}$ | Q_r | | | 3,6 | μAs |
| | $T_{vj} = 25^{\circ}\text{C}$ | | | | 7,6 | |
| | $T_{vj} = 125^{\circ}\text{C}$ | | | | 7,6 | μAs |

Thermische Eigenschaften / Thermal properties

Zieldaten Target data

| | | | | |
|---|---|------------------|-------------|--------------------|
| Innerer Wärmewiderstand thermal resistance, junction to case | Netz-Diode / Rectifier diode, $\theta = 120^\circ\text{rect}$ | R_{thJC} | max. 0,63 | $^\circ\text{C/W}$ |
| | Transistor / Transistor, DC | | max. 0,25 | $^\circ\text{C/W}$ |
| | Schnelle Diode / Fast diode, DC | | max. 0,80 | $^\circ\text{C/W}$ |
| Übergangs-Wärmewiderstand thermal resistance, case to heatsink | Netz-Diode / Rectifier diode | R_{thCK} | max. 0,25 | $^\circ\text{C/W}$ |
| | Transistor / Transistor | | max. 0,16 | $^\circ\text{C/W}$ |
| | Schnelle Diode / Fast diode | | max. 0,24 | $^\circ\text{C/W}$ |
| Höchstzulässige Sperrschichttemperatur max. junction temperature | | $T_{vj\max}$ | 125 | $^\circ\text{C}$ |
| Betriebstemperatur operating temperature | | $T_{c\text{op}}$ | - 40...+125 | $^\circ\text{C}$ |
| Lagertemperatur storage temperature | | T_{stg} | - 40...+130 | $^\circ\text{C}$ |

Mechanische Eigenschaften / Mechanical properties

| | | | | |
|---|---------------------------------|----|-------------------------|----------------|
| Gehäuse, siehe Anlage case, see appendix | | | Seite 4 page 4 | |
| Innere Isolation internal insulation | | | Al_2O_3 | |
| Anzugsdrehmoment für mechanische Befestigung mounting torque | Toleranz / tolerance $\pm 15\%$ | M1 | 4 | Nm |
| Gewicht weight | | G | typ. 185 | g |
| Kriechstrecke creepage distance | | | 12,5 | mm |
| Schwingfestigkeit vibration resistance | $f = 50\text{Hz}$ | | 50 | m/s^2 |

Temperatursensor / Temperature sensor

| | | | | |
|--------------------------------------|---|----------|---------|------------------|
| Nennwiderstand rated resistance | $T_C = 25^\circ\text{C}$ $R_{100} = 493\Omega \pm 5\%$ | R_{25} | 5 | $\text{k}\Omega$ |
| Verlustleistung power dissipation | $T_C = 25^\circ\text{C}$ | P_{25} | max. 20 | mW |

Kühlkörper / heatsinks :

Mit dieser technischen Information werden Halbleiterbauelemente spezifiziert, jedoch keine Eigenschaften zugesichert. Sie gilt in Verbindung mit den zugehörigen Technischen Erläuterungen. / This technical information specifies semiconductor devices but promises no characteristics. It is valid in combination with the belonging technical notes.

